

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4864697

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIN-YU CHEN	03/12/2018
CHENG-WEN CHEN	03/12/2018
SHUN-JUNG CHUANG	03/12/2018
KE-HAO CHEN	03/12/2018
RECEIVING PARTY DATA	
Name:	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
Street Address:	Floor 4, Willow House, Cricket Square, P O Box 2804
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15920413
CORRESPONDENCE DATA	
Fax Number:	(408)919-8353
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4089196137
Email:	joseph.chung@fit-foxconn.com,sou-proce7@foxconn.com,sou-proce7@fit-foxconn.com
Correspondent Name:	WEI TE CHUNG
Address Line 1:	408 E PLUMERIA DR.
Address Line 4:	SAN JOSE, CALIFORNIA 95134
ATTORNEY DOCKET NUMBER:	US61755
NAME OF SUBMITTER:	WEI TE CHUNG
SIGNATURE:	/WEI TE CHUNG/
DATE SIGNED:	03/13/2018
Total Attachments: 2	
source=US61755180313ASM#page1.tif	
source=US61755180313ASM#page2.tif	

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. CHIN-YU CHEN , residing at New Taipei, Taiwan
- 2. CHENG-WEN CHEN , residing at New Taipei, Taiwan
- 3. SHUN-JUNG CHUANG , residing at New Taipei, Taiwan
- 4. KE-HAO CHEN , residing at New Taipei, Taiwan
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **FOXCONN INTERCONNECT TECHNOLOGY LIMITED** having a principal place of business at **Floor 4, Willow House, Cricket Square, P O Box 2804, Grand Cayman KY1-1112 , Cayman Islands**, hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **MULTI-LAYER CIRCUIT MEMBER WITH REFERENCE PLANES AND GROUND LAYER SURROUNDING AND SEPARATING CONDUCTIVE SIGNAL PADS** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Chin-Yu Chen</u> CHIN-YU CHEN	<u>03/12/2018</u> Date
2.	<u>CHENG-WEN CHEN</u> CHENG-WEN CHEN	<u>03/12/2018</u> Date
3.	<u>Shun-Jung Chuang</u> SHUN-JUNG CHUANG	<u>03/12/2018</u> Date
4.	<u>KE-HAO CHEN</u> KE-HAO CHEN	<u>03/12/2018</u> Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date